

# PMEG060T060CLPE

60 V, 2 x 3 A dual common cathode low leakage current Trench MEGA Schottky barrier rectifier

27 April 2020 Product data sheet

# 1. General description

Trench Maximum Efficiency General Application (MEGA) dual Schottky barrier rectifier in common cathode configuration encapsulated in a CFP15B (SOT1289B) power and flat lead Surface-Mounted Device (SMD) plastic package.

## 2. Features and benefits

- Reverse voltage: V<sub>R</sub> ≤ 60 V
- Forward current: I<sub>F</sub> ≤ 3 A (per diode)
- Low forward voltage
- Low leakage current due to Trench MEGA Schottky technology
- Power and flat lead SMD plastic package
- · Package height typical 0.95 mm
- · High power capability due to clip-bond technology
- AEC-Q101 qualified

# 3. Applications

- · Low voltage rectification
- · High efficiency DC-to-DC conversion
- · Switch mode power supply
- Reverse polarity protection
- Low power consumption applications
- Freewheeling applications

### 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit		
Per diode (u	Per diode (unless otherwise specified)								
I <sub>F(AV)</sub>	average forward current	$\delta$ = 0.5; square wave; f = 20 kHz; T <sub>sp</sub> ≤ 165 °C		-	-	3	А		
$V_R$	reverse voltage	T <sub>j</sub> = 25 °C		-	-	60	V		
$V_{F}$	forward voltage	I <sub>F</sub> = 3 A; T <sub>j</sub> = 25 °C	[1]	-	550	620	mV		
I <sub>R</sub>	reverse current	V <sub>R</sub> = 10 V; T <sub>j</sub> = 25 °C	[1]	-	0.14	0.9	μA		
		V <sub>R</sub> = 60 V; T <sub>j</sub> = 25 °C	[1]	-	0.3	1.8	μΑ		

[1] Very short pulse, in order to maintain a stable junction temperature.



# 5. Pinning information

#### **Table 2. Pinning information**

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	A1	anode (diode 1)	5	CC
2	A2	anode (diode 2)		
3	CC	common cathode	CFP15B (SOT1289B)	A1 A2 006aab034

# 6. Ordering information

#### **Table 3. Ordering information**

Type number	Package						
	Name	Description	Version				
PMEG060T060CLPE	CFP15B	plastic, thermal enhanced ultra thin SMD package; 3 leads; 2.13 mm pitch; 5.8 x 4.3 x 0.95 mm body	SOT1289B				

# 7. Marking

#### Table 4. Marking codes

Type number	Marking code
PMEG060T060CLPE	060T L06C

# 8. Limiting values

### Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC60134)

Symbol	Parameter	Conditions		Min	Max	Unit
Per diode (	(unless otherwise specified)			<u> </u>		
V <sub>R</sub>	reverse voltage	T <sub>j</sub> = 25 °C		-	60	V
l <sub>F</sub>	forward current	δ = 1; T <sub>sp</sub> ≤ 162 °C		-	4.2	Α
I <sub>F(AV)</sub>	average forward current	$\delta$ = 0.5; square wave; f = 20 kHz; T <sub>sp</sub> ≤ 165 °C		-	3	А
I <sub>FSM</sub>	non-repetitive peak	$t_p$ = 8.3 ms; half sine wave; $T_{j(init)}$ = 25 °C		-	80	Α
	forward current	t <sub>p</sub> = 8.3 ms; half sine wave; per device; T <sub>j(init)</sub> = 25 °C		-	150	А
Per device	, one diode loaded			'		_
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C	[1]	-	1.66	W
			[2]	-	2.15	W
Tj	junction temperature			-	175	°C
T <sub>amb</sub>	ambient temperature			-55	175	°C
T <sub>stg</sub>	storage temperature			-65	175	°C

Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.

# 9. Thermal characteristics

**Table 6. Thermal characteristics** 

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
Per device, on	e diode loaded				71		
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	in free air	[1] [2]	-	-	90	K/W
			[1] [3]	-	-	70	K/W
R <sub>th(j-sp)</sub>	thermal resistance from junction to solder point		[4]	-	-	7	K/W

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P<sub>R</sub> are a significant part of the total power losses.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.
- [4] Soldering point of cathode tab.

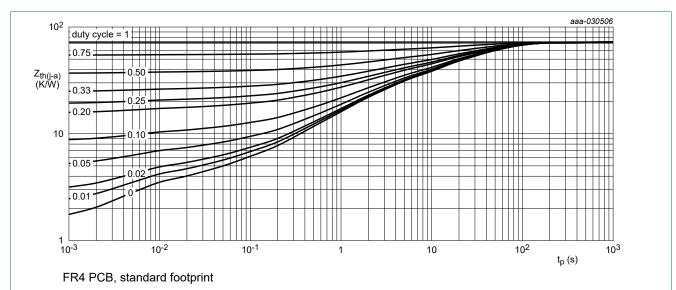


Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

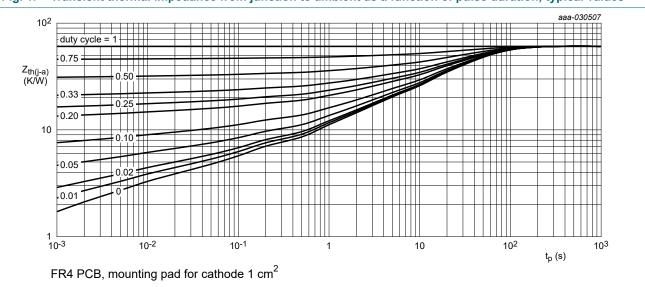


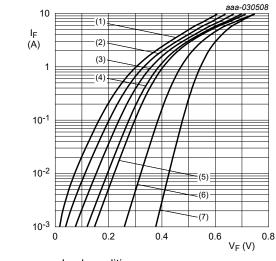
Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

# 10. Characteristics

**Table 7. Characteristics** 

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
Per diode (ı	unless otherwise specified	)					
$V_{(BR)R}$	reverse breakdown voltage	I <sub>R</sub> = 1 mA; T <sub>j</sub> = 25 °C	[1]	60	-	-	V
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 0.5 A; T <sub>j</sub> = 25 °C	[1]	-	440	510	mV
		I <sub>F</sub> = 1 A; T <sub>j</sub> = 25 °C	[1]	-	470	540	mV
		I <sub>F</sub> = 3 A; T <sub>j</sub> = 25 °C	[1]	-	550	620	mV
		I <sub>F</sub> = 3 A; T <sub>j</sub> = -40 °C	[1]	-	600	680	mV
		I <sub>F</sub> = 3 A; T <sub>j</sub> = 125 °C	[1]	-	480	570	mV
I <sub>R</sub>	reverse current	V <sub>R</sub> = 10 V; T <sub>j</sub> = 25 °C	[1]	-	0.14	0.9	μΑ
		V <sub>R</sub> = 40 V; T <sub>j</sub> = 25 °C	[1]	-	0.18	1.2	μΑ
		V <sub>R</sub> = 60 V; T <sub>j</sub> = 25 °C	[1]	-	0.3	1.8	μΑ
		V <sub>R</sub> = 60 V; T <sub>j</sub> = 125 °C	[1]	-	0.5	3	mA
C <sub>d</sub>	diode capacitance	$V_R = 1 \text{ V; } f = 1 \text{ MHz; } T_j = 25 \text{ °C}$		-	560	-	pF
		V <sub>R</sub> = 10 V; f = 1 MHz; T <sub>j</sub> = 25 °C		-	180	-	pF
t <sub>rr</sub>	reverse recovery time step recovery	$I_F = 0.5 \text{ A}; I_R = 0.5 \text{ A}; I_{R(meas)} = 0.1 \text{ A};$ $T_j = 25 \text{ °C}$		-	17	-	ns
	reverse recovery time ramp recovery	$dI_F/dt = 200 \text{ A/}\mu\text{s}; I_F = 6 \text{ A}; V_R = 26 \text{ V};$ $T_j = 25 ^{\circ}\text{C}$		-	11	-	ns
$V_{FRM}$	peak forward recovery voltage	$I_F = 0.5 \text{ A}; dI_F/dt = 20 \text{ A/}\mu\text{s}; T_j = 25 ^{\circ}\text{C}$		-	460	-	mV

<sup>[1]</sup> Very short pulse, in order to maintain a stable junction temperature.



pulsed condition

(1)  $T_i = 175 \,^{\circ}C$ 

(2)  $T_i = 150 °C$ 

 $(3) T_j = 125 °C$ 

 $(4) T_j = 100 °C$ 

(5)  $T_j = 85 \,^{\circ}\text{C}$ 

(6)  $T_j = 25 \,^{\circ}\text{C}$ (7)  $T_i = -40 \,^{\circ}\text{C}$ 

Fig. 3. Forward current as a function of forward voltage; typical values

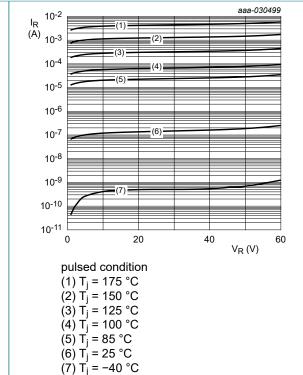


Fig. 4. Reverse current as a function of reverse voltage; typical values

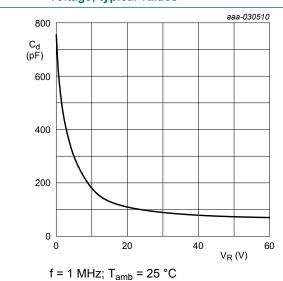
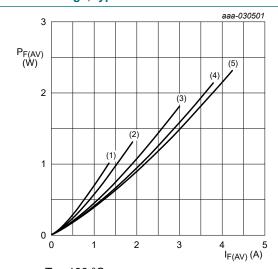


Fig. 5. Diode capacitance as a function of reverse voltage; typical values



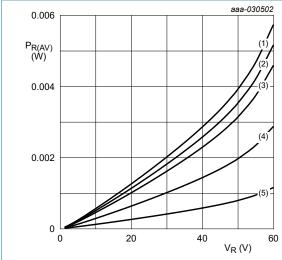
 $T_j = 100 \,^{\circ}\text{C}$ (1)  $\delta = 0.1$ (2)  $\delta = 0.2$ 

 $(3) \delta = 0.5$ 

 $(4) \delta = 0.8$ 

(5)  $\delta = 1$ ; DC

Fig. 6. Average forward power dissipation as a function of average forward current; typical values



 $T_i = 100 \, ^{\circ}C$ 

 $(1) \delta = 1$ ; DC

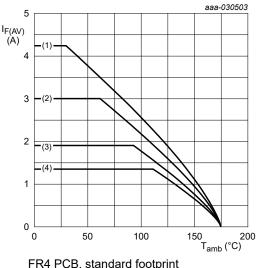
 $(2) \delta = 0.9$ 

 $(3) \delta = 0.8$ 

 $(4) \delta = 0.5$ 

 $(5) \delta = 0.2$ 

Fig. 7. Average reverse power dissipation as a function of reverse voltage; typical values



FR4 PCB, standard footprint

 $T_i = 175 \,{}^{\circ}\text{C}$ 

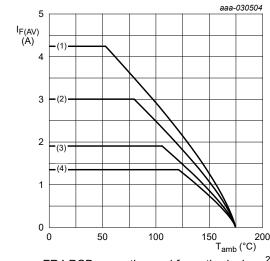
 $(1) \delta = 1$ ; DC

(2)  $\delta = 0.5$ ; f = 20 kHz

(3)  $\delta = 0.2$ ; f = 20 kHz

(4)  $\delta = 0.1$ ; f = 20 kHz

Average forward current as a function of Fig. 8. ambient temperature; typical values



FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>

T<sub>i</sub> = 175 °C

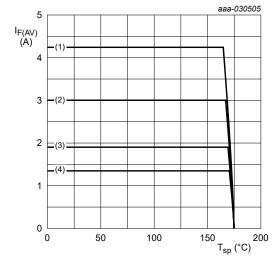
 $(1) \delta = 1$ ; DC

(2)  $\delta = 0.5$ ; f = 20 kHz

(3)  $\delta = 0.2$ ; f = 20 kHz

(4)  $\delta = 0.1$ ; f = 20 kHz

Fig. 9. Average forward current as a function of ambient temperature; typical values



 $T_i = 175 \,{}^{\circ}\text{C}$ 

 $(1) \delta = 1; DC$ 

(2)  $\delta = 0.5$ ; f = 20 kHz

(3)  $\delta = 0.2$ ; f = 20 kHz

(4)  $\delta = 0.1$ ; f = 20 kHz

Fig. 10. Average forward current as a function of solder point temperature; typical values

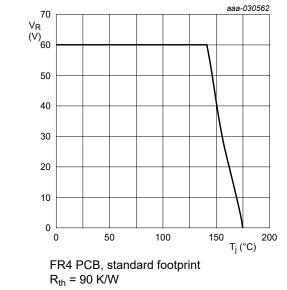
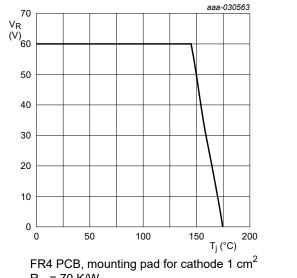


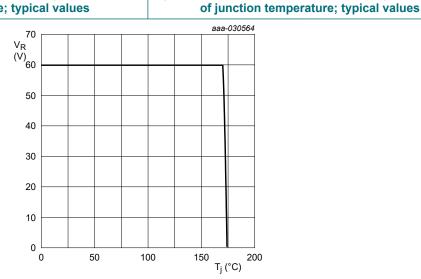
Fig. 11. Derated maximum reverse voltage as a function of junction temperature; typical values

Fig. 12. Derated maximum reverse voltage as a function of junction temperature; typical values



R<sub>th</sub> = 70 K/W

Derated maximum reverse voltage as a funct



Soldering point of cathode tab R<sub>th</sub> = 7 K/W

Fig. 13. Derated maximum reverse voltage as a function of junction temperature; typical values

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# 11. Test information

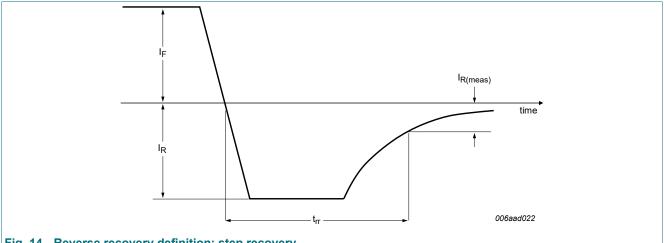


Fig. 14. Reverse recovery definition; step recovery

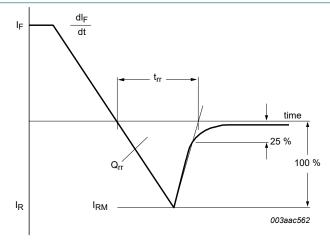


Fig. 15. Reverse recovery definition; ramp recovery

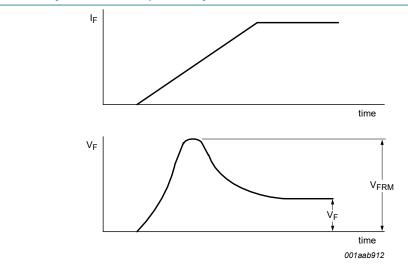
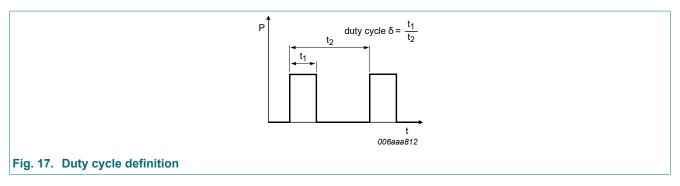


Fig. 16. Forward recovery definition



The current ratings for the typical waveforms are calculated according to the equations:

 $I_{F(AV)}=I_M\times\delta$  with  $I_M$  defined as peak current

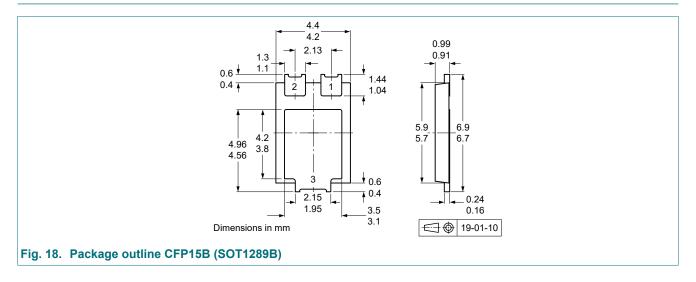
 $I_{RMS} = I_{F(AV)}$  at DC, and  $I_{RMS} = I_{M} \times \sqrt{\delta}$ 

with I<sub>RMS</sub> defined as RMS current.

### **Quality information**

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

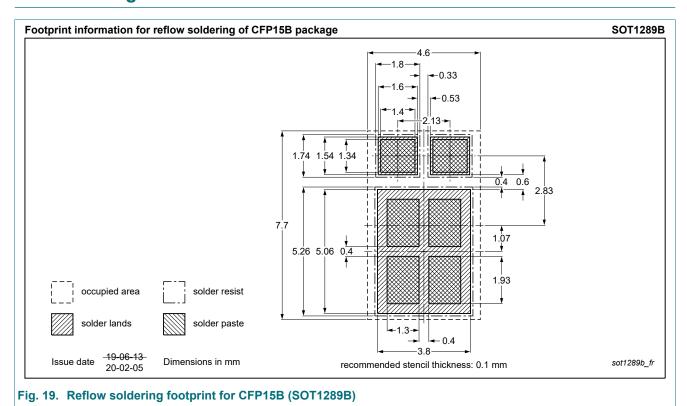
# 12. Package outline



Downloaded from Arrow.com.

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# 13. Soldering



# 14. Revision history

#### Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG060T060CLPE v.2	20200427	Product data sheet	-	PMEG060T060CLPE v.1
Modifications:	Product status of	changed		
PMEG060T060CLPE v.1	20200304	Objective data sheet	-	-

# 15. Legal information

#### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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